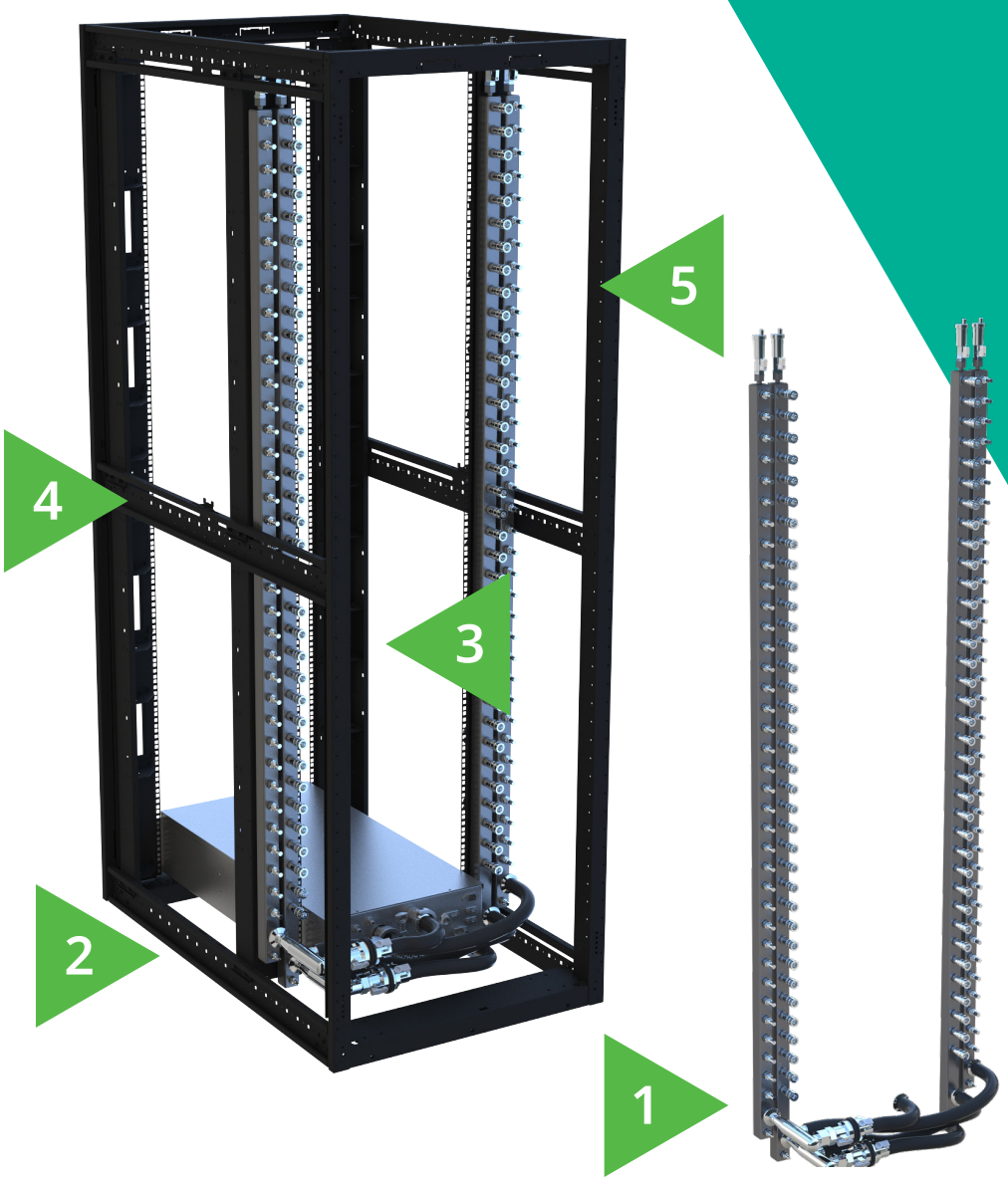
PANDUIT™

Cool Smarter. Perform Better.

Direct to Chip Cooling engineered for AI and HPC environments.



1 READY FOR YOUR LARGEST AI SERVERS

The Panduit Rack Manifold is an essential element of the Direct-to-Chip Cooling cabinet ecosystem. Designed for a quick and easy installation.

2 STANDARD FOOTPRINT, NO ADD ONS

Unique cabinet and rack manifold design maximizes the amount of usable space in the rear of the cabinet. Supports multiple manifolds and PDUs for high-density cooling.

3 ACCELERATE DEPLOYMENT, REDUCE RISK

Extra space makes it easier to outfit AI and HPC cabinets with liquid cooling manifolds, multiple PDUs, power cords, and fiber optic cabling management.

4 QUICK SWAP COMPONENTS

Designed to alleviate overcrowding in cabinets that support AI and HPC workloads within on-premises and colocation data centers and deployments at the edge.

5 FLEX FUSION CABINET

Consist of movable e-rails capable of supporting up to four DTC manifolds or PDUs.

For more information on the DTC Cooling, visit **panduit.com/dtc**

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